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(54) **STACKED SEMICONDUCTOR DIE ASSEMBLIES WITH HIGH EFFICIENCY THERMAL PATHS AND ASSOCIATED SYSTEMS**

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See application file for complete search history.

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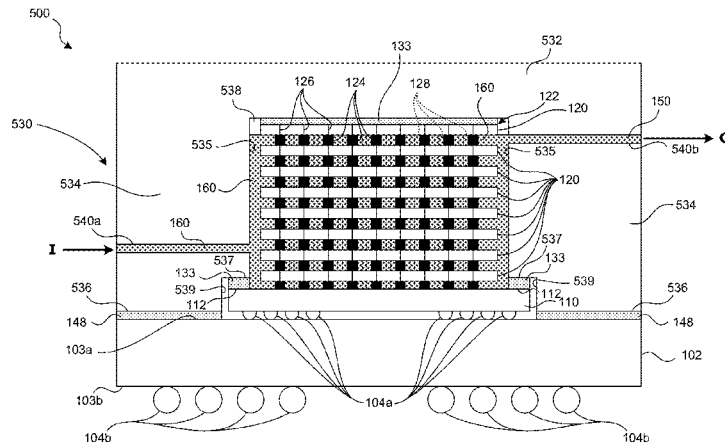
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ABSTRACT

Semiconductor die assemblies having high efficiency thermal paths. In one embodiment, a semiconductor die assembly comprises a package support substrate, a first semiconductor die electrically mounted to the package support substrate, and a plurality of second semiconductor dies. The first die has a stacking site and a peripheral region extending laterally from the stacking site, and the bottom second semiconductor die is attached to the stacking site of the first die. The assembly further includes (a) a thermal transfer structure attached to the peripheral region of the first die that has a cavity in which the second dies are positioned and an inlet, and (b) an underfill material in the cavity. The underfill material has a fillet between the second semiconductor dies caused by injecting the underfill material into the cavity through the inlet port of the casing.

28 Claims, 20 Drawing Sheets



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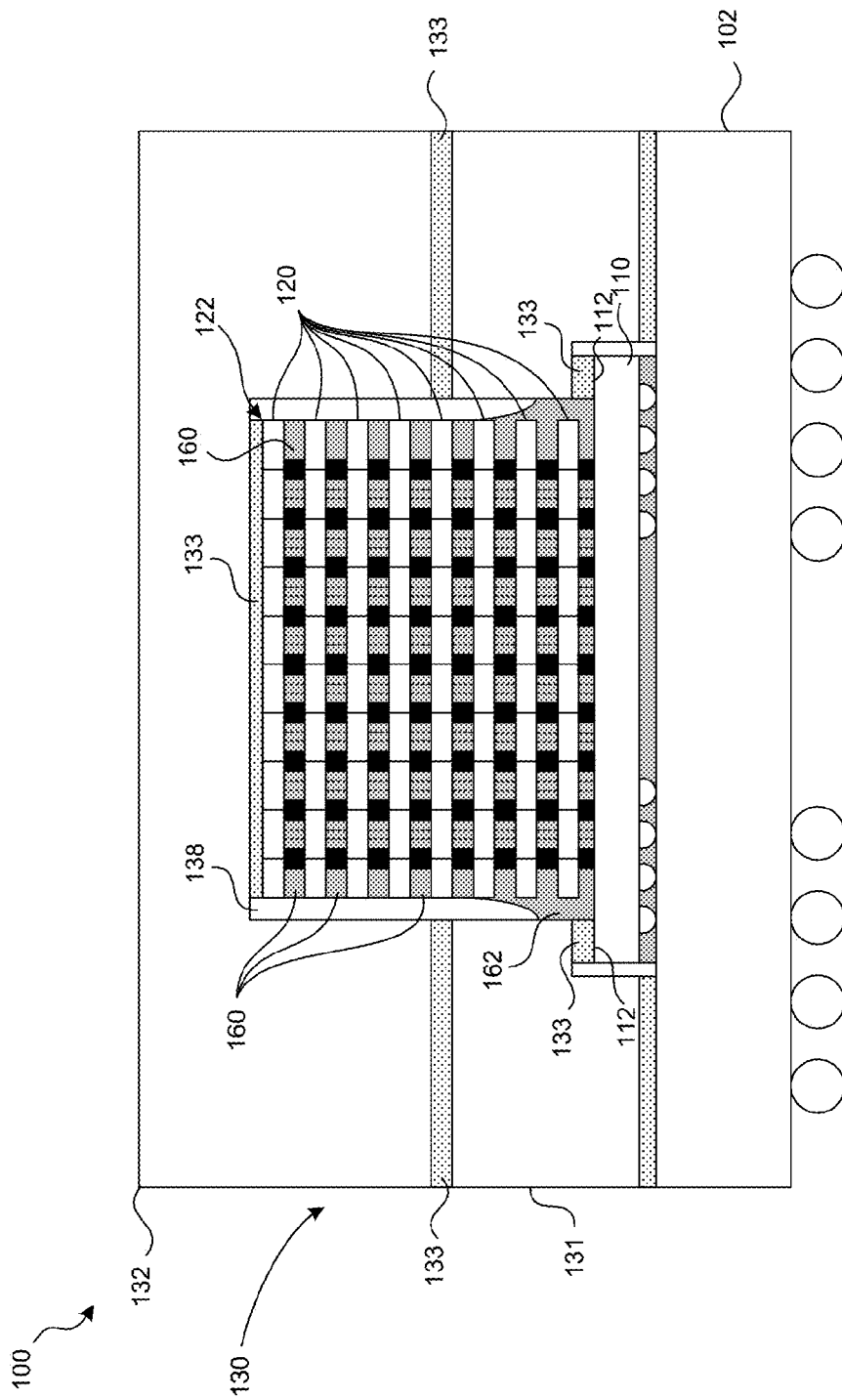


FIG. 1

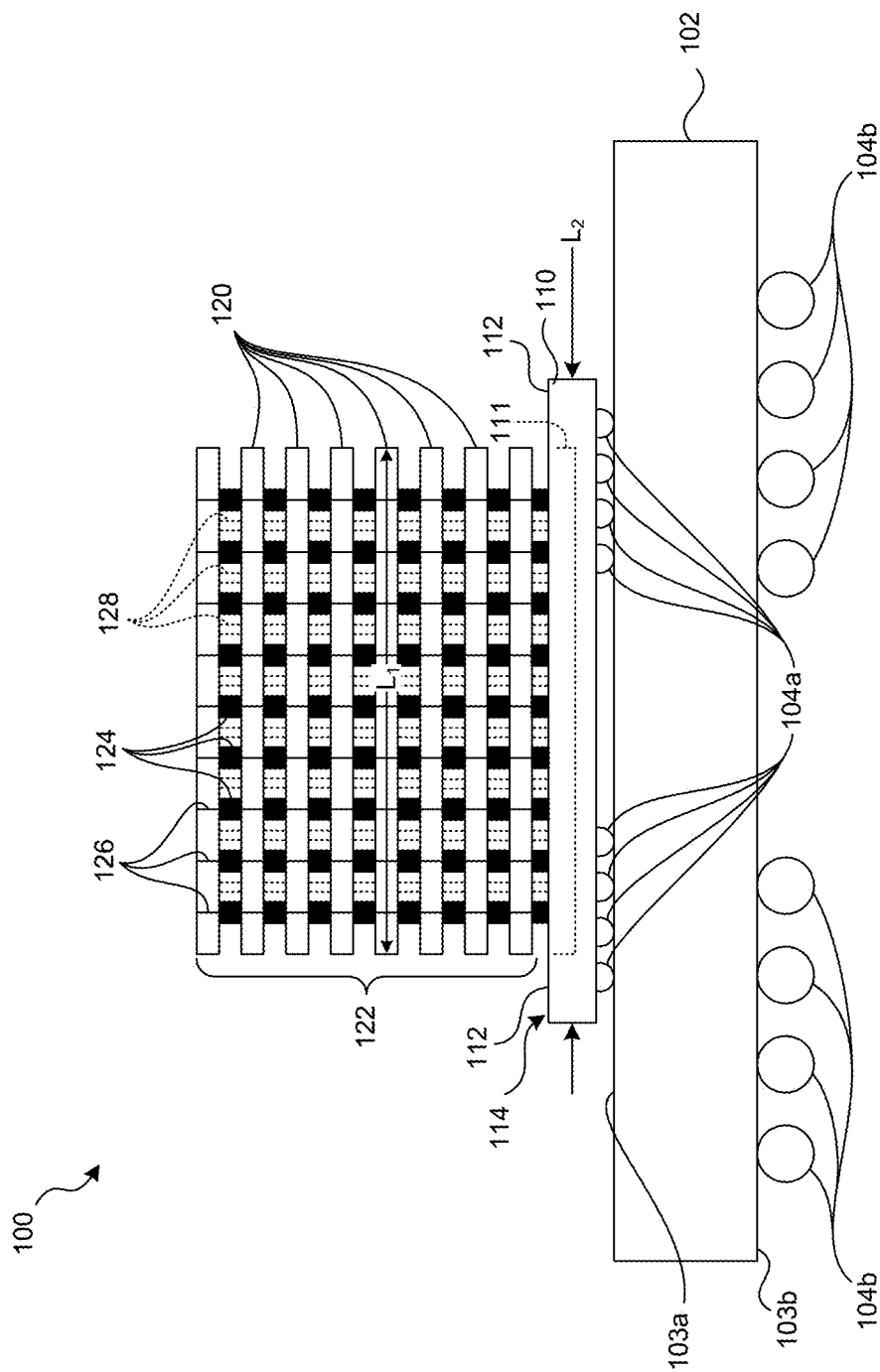


FIG. 2A

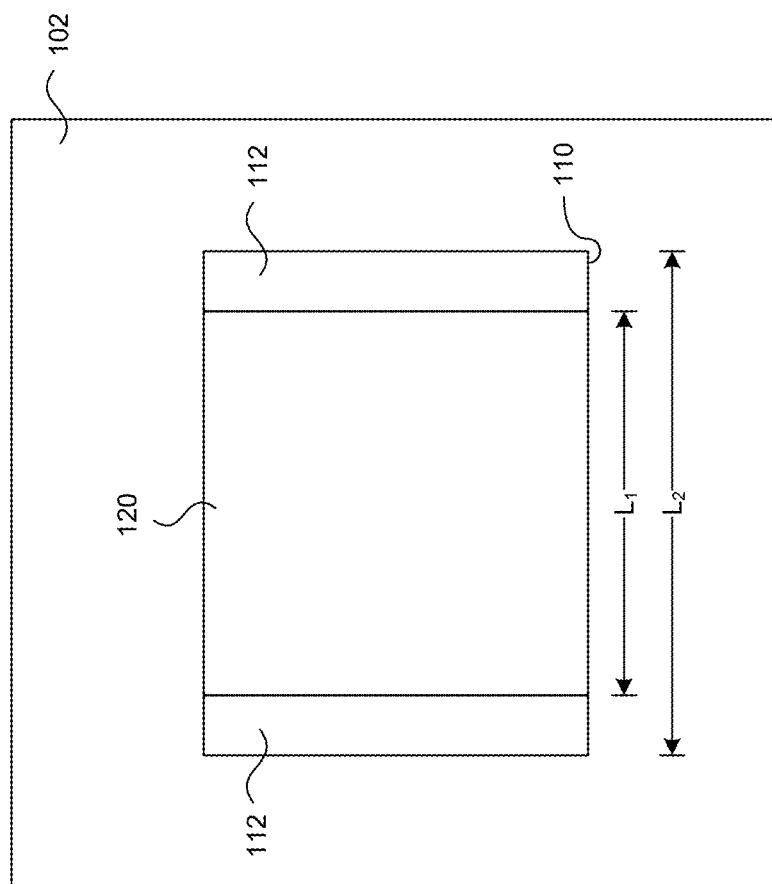


FIG. 2B

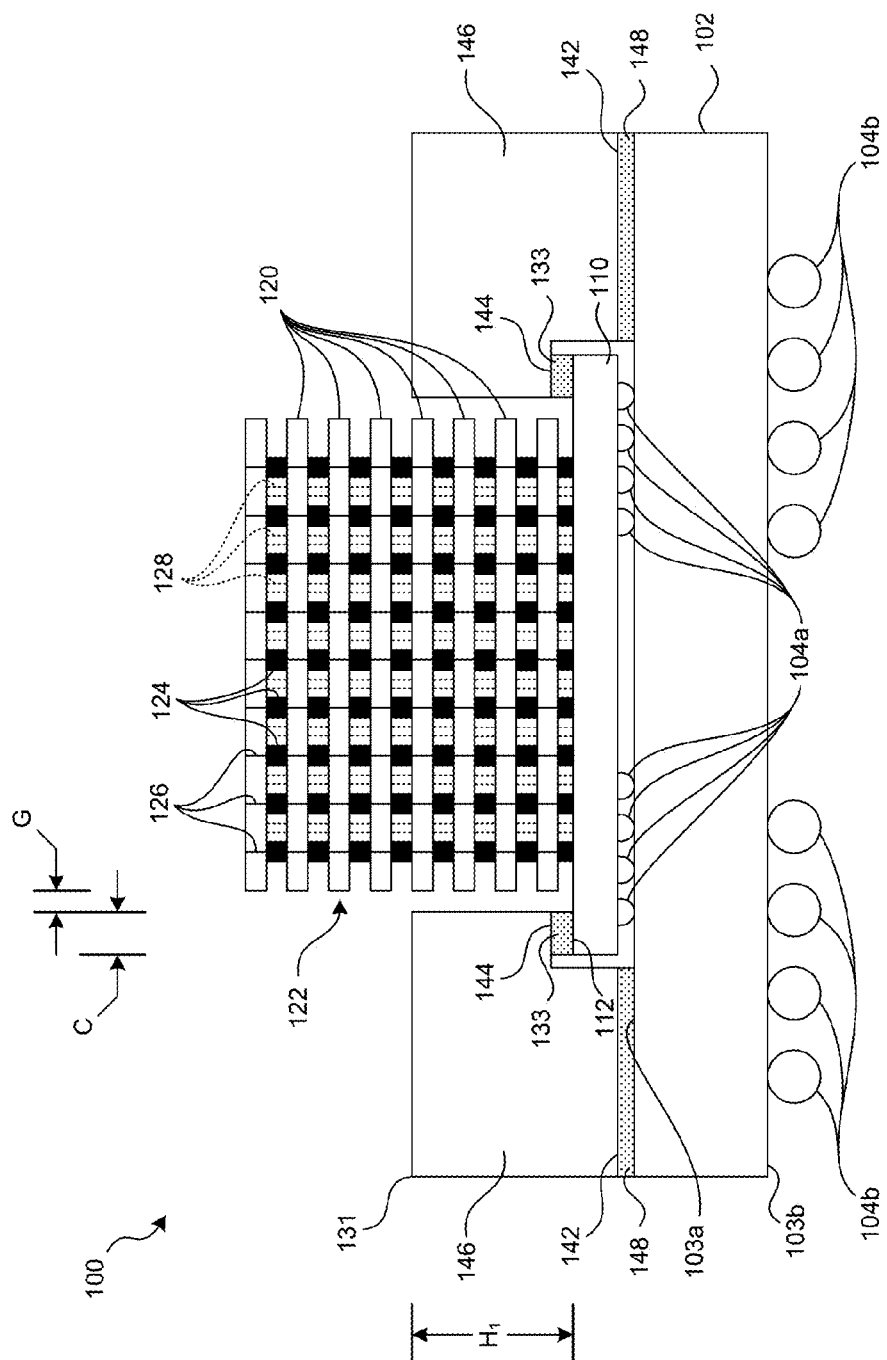


FIG. 2C

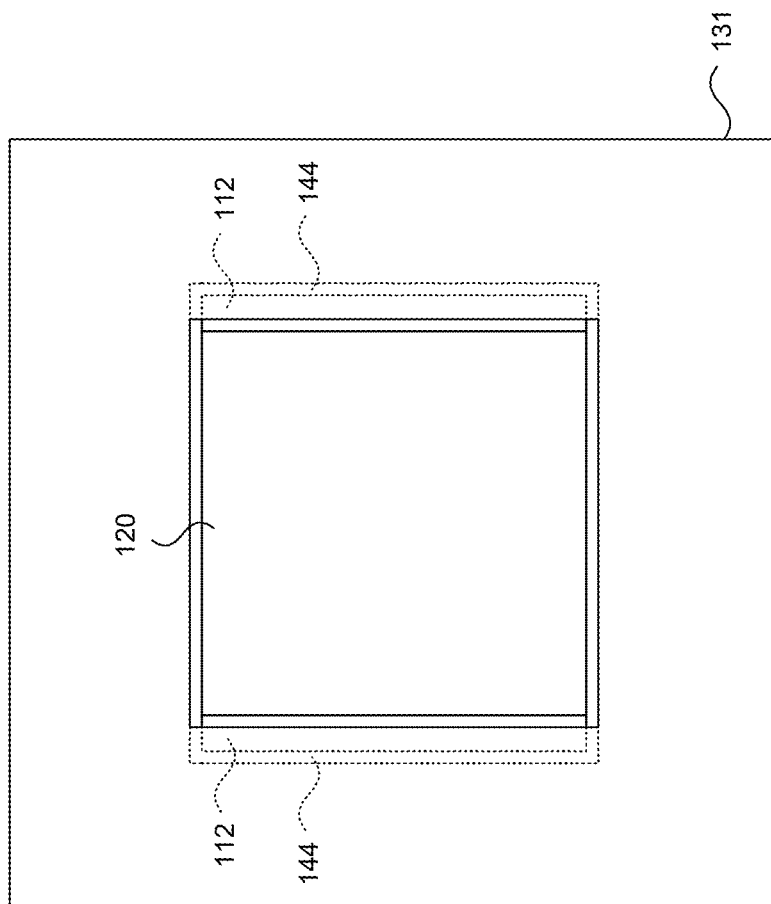


FIG. 2D

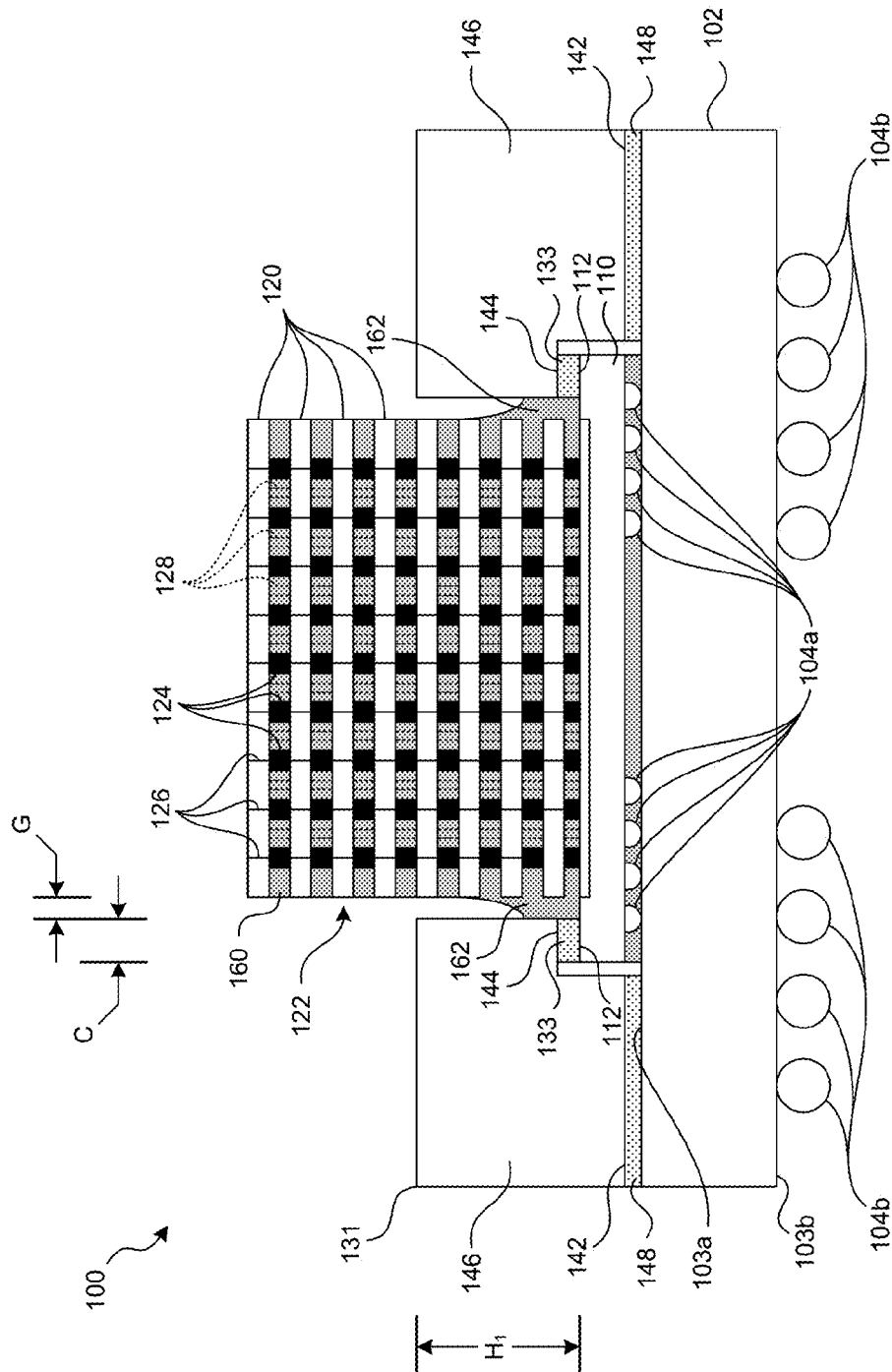


FIG. 2E

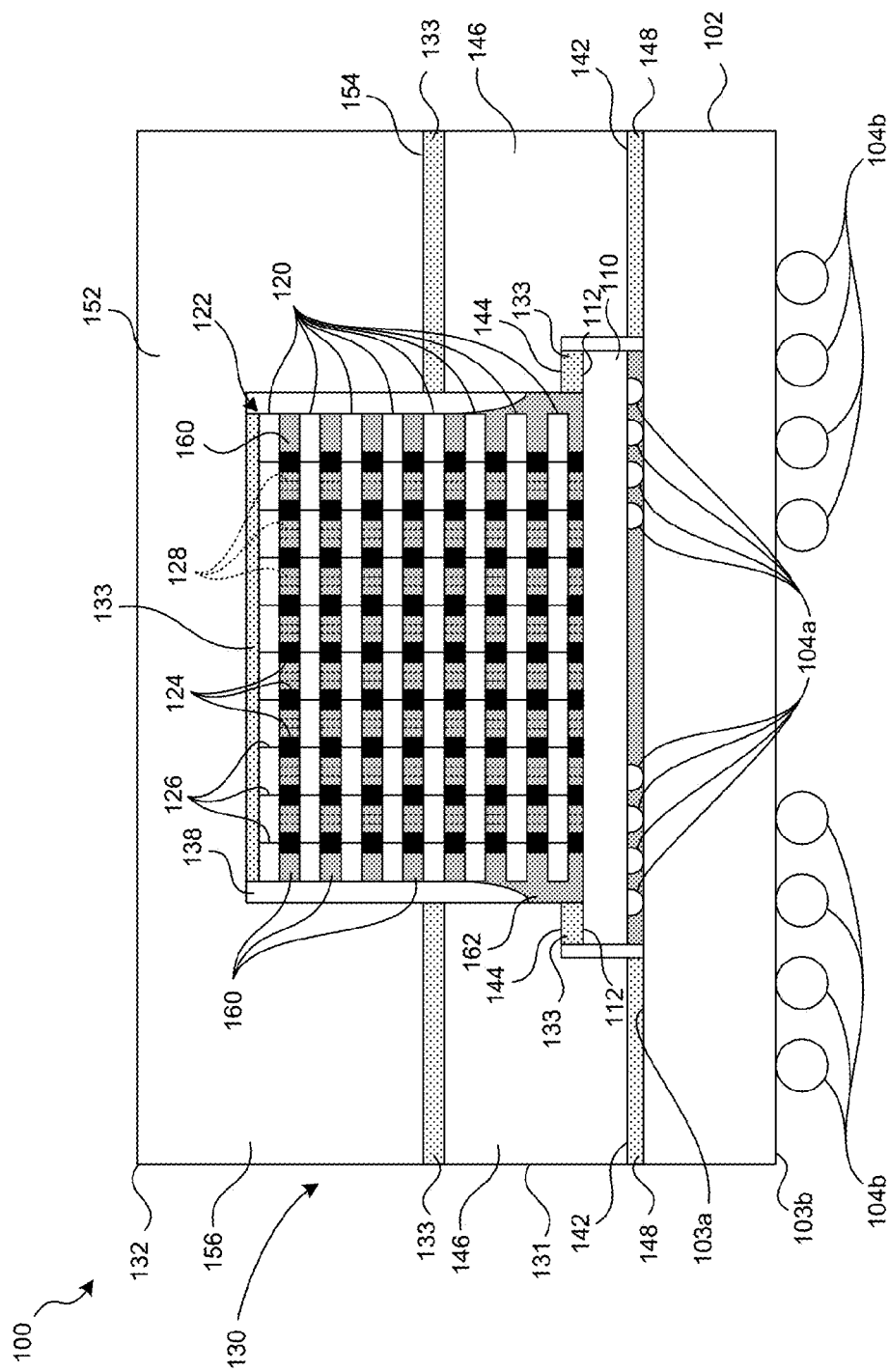


FIG. 2F

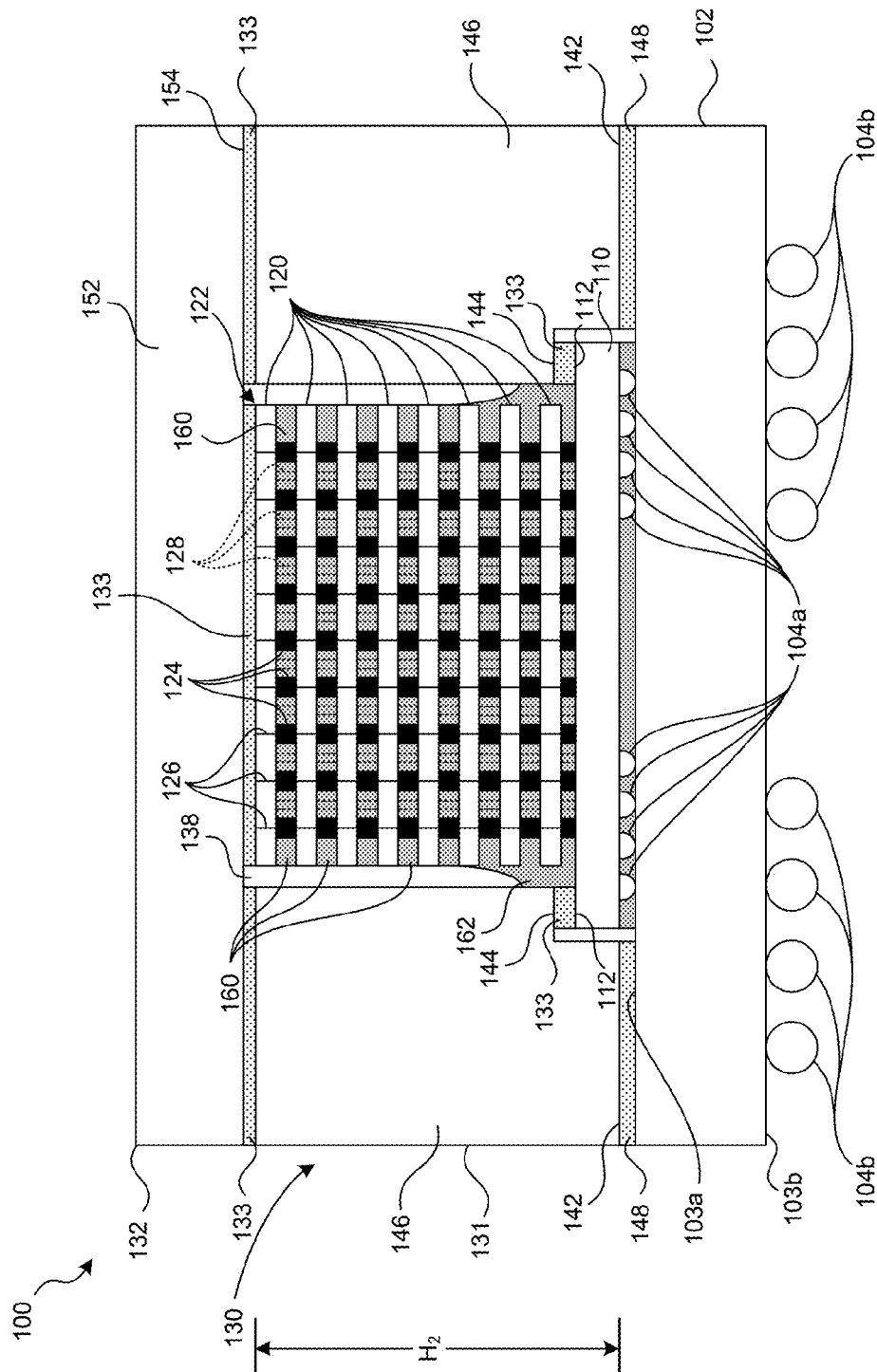


FIG. 3

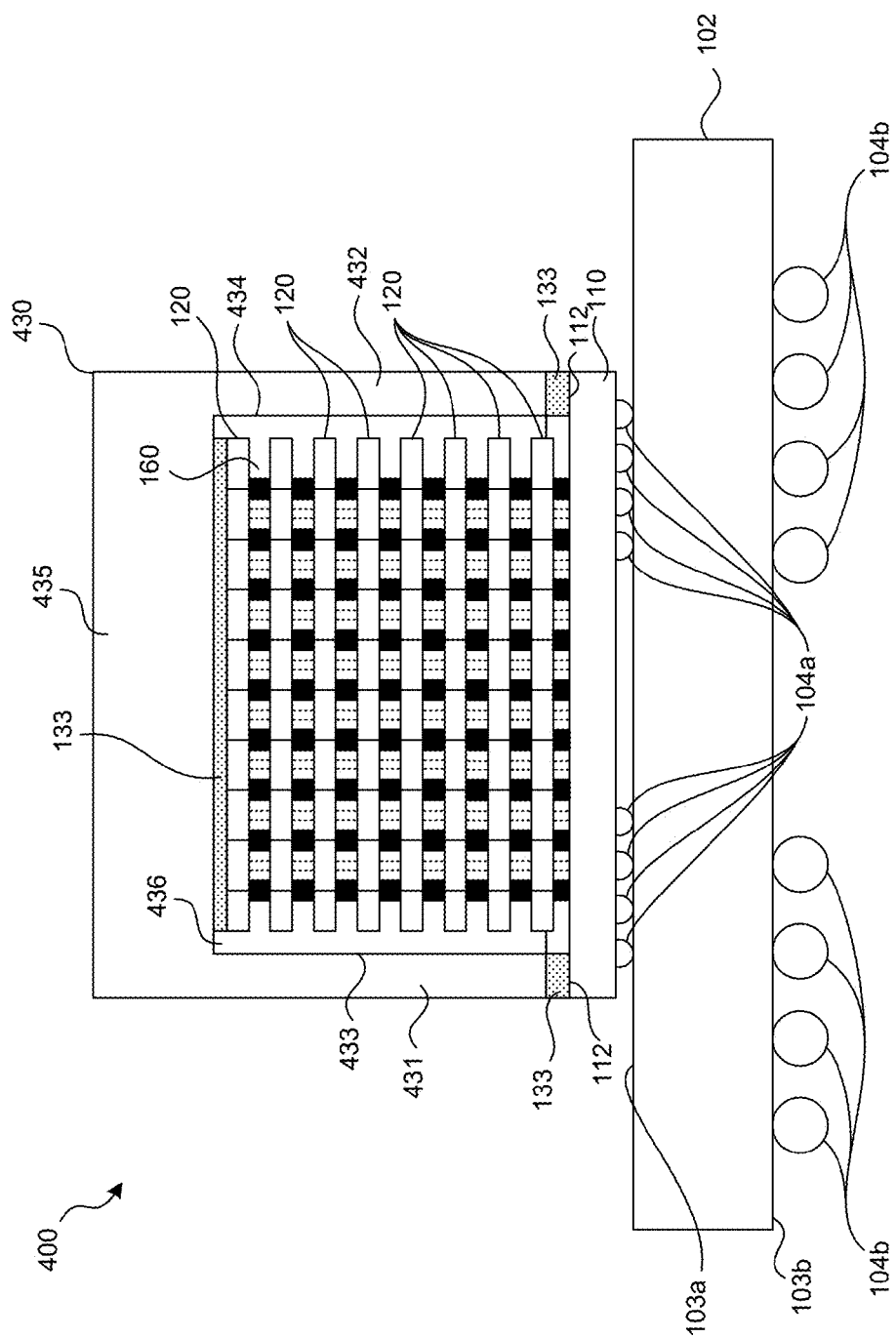


FIG. 4A

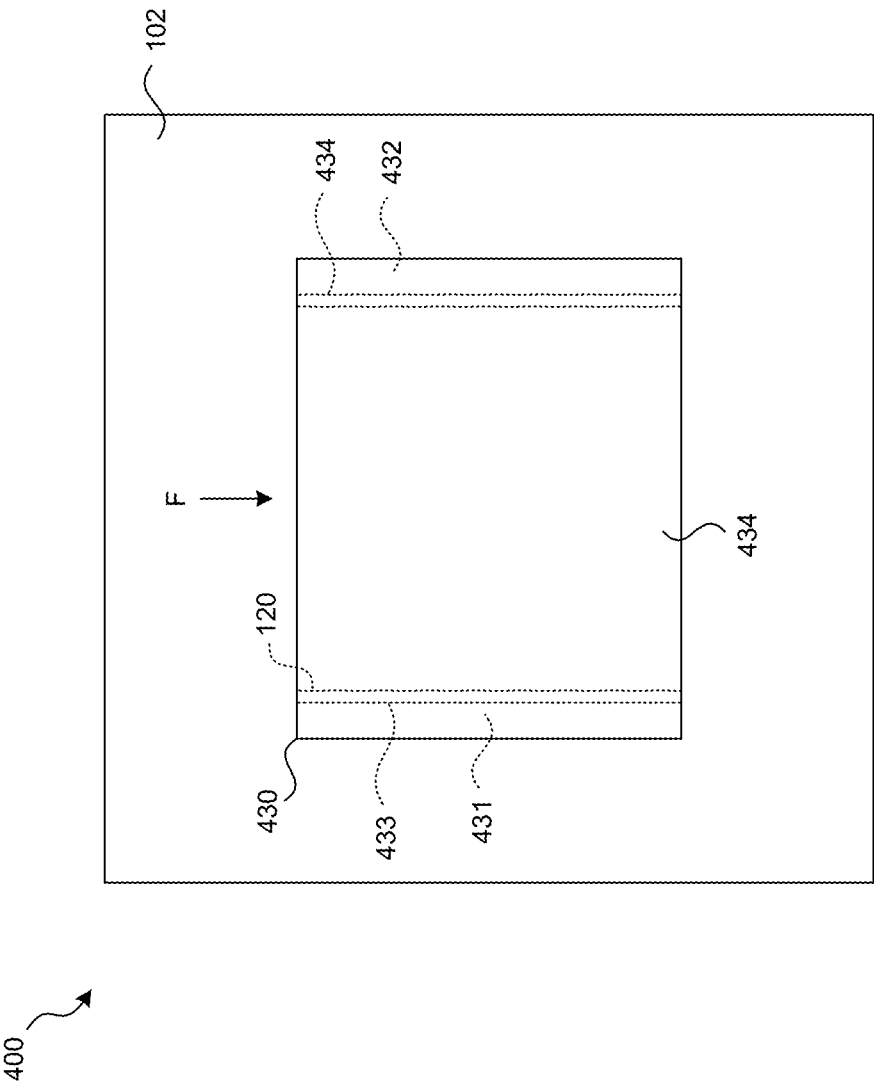


FIG. 4B

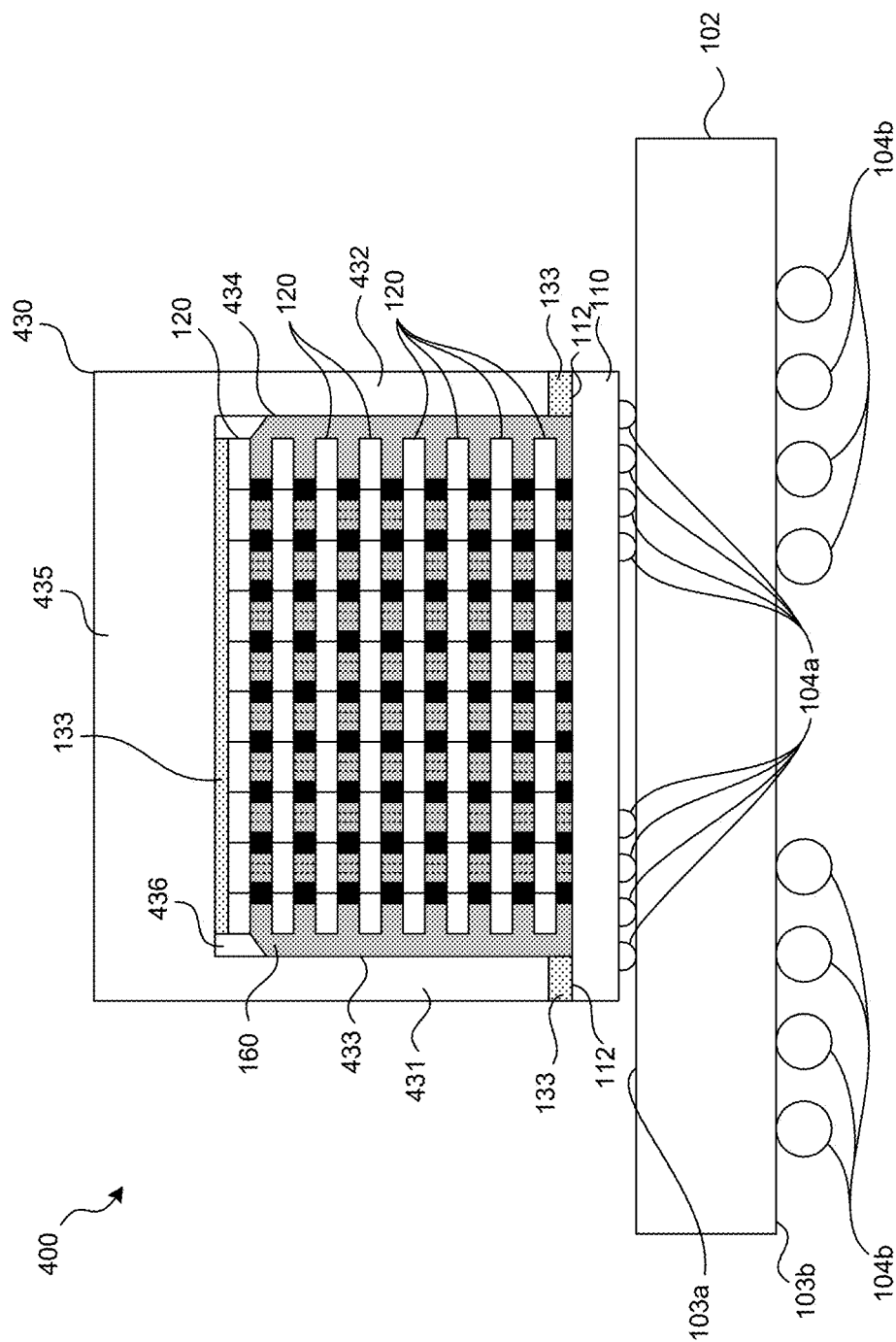


FIG. 4C

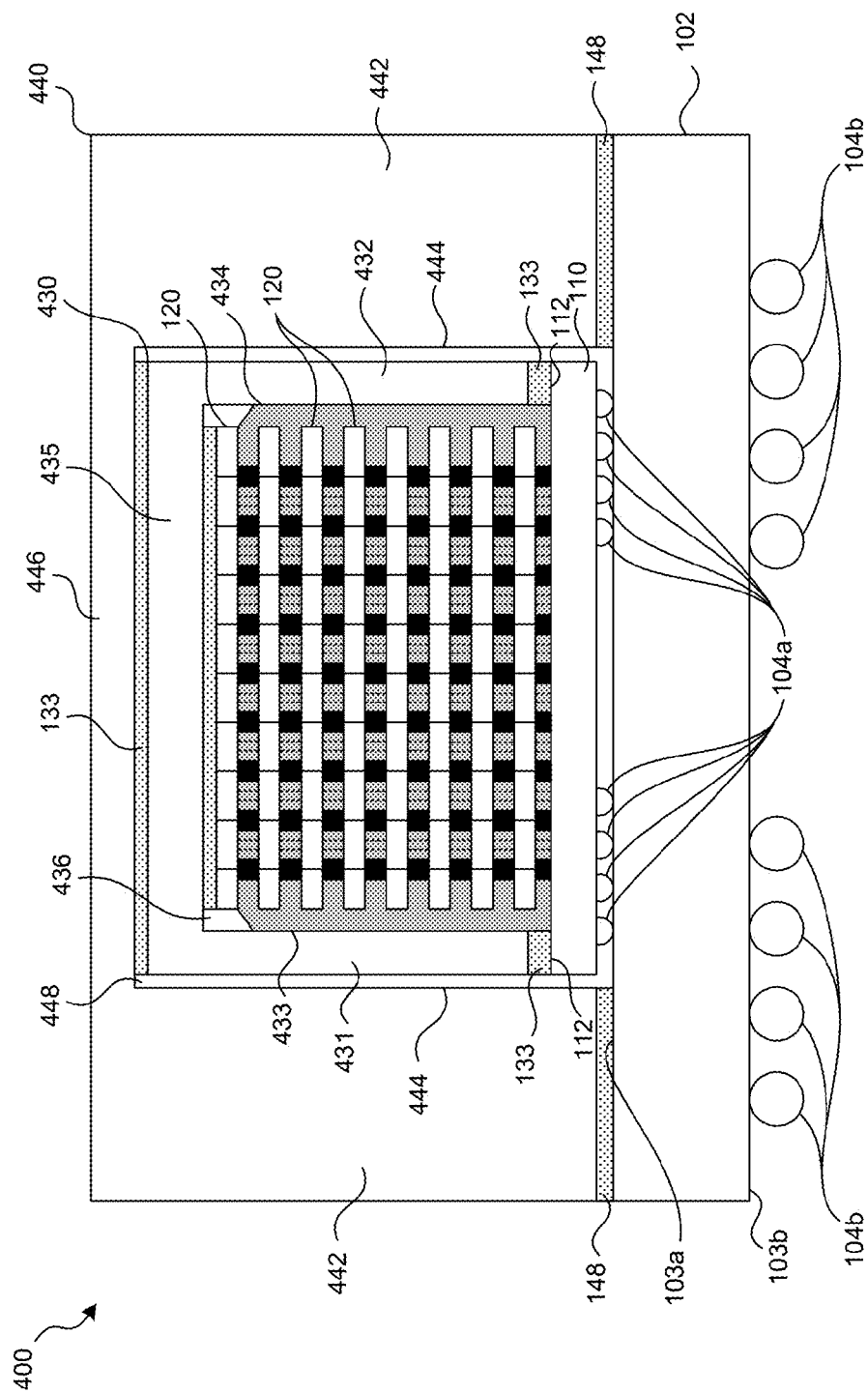


FIG. 4D

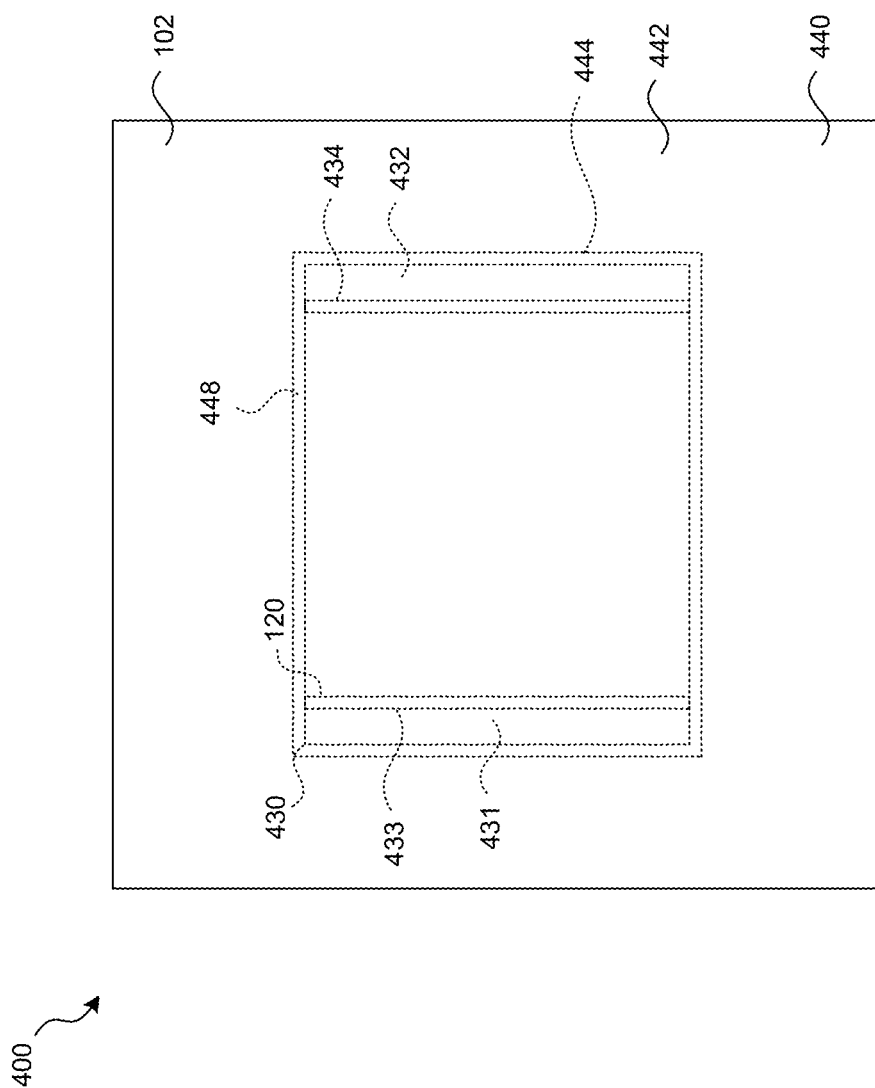


FIG. 4E

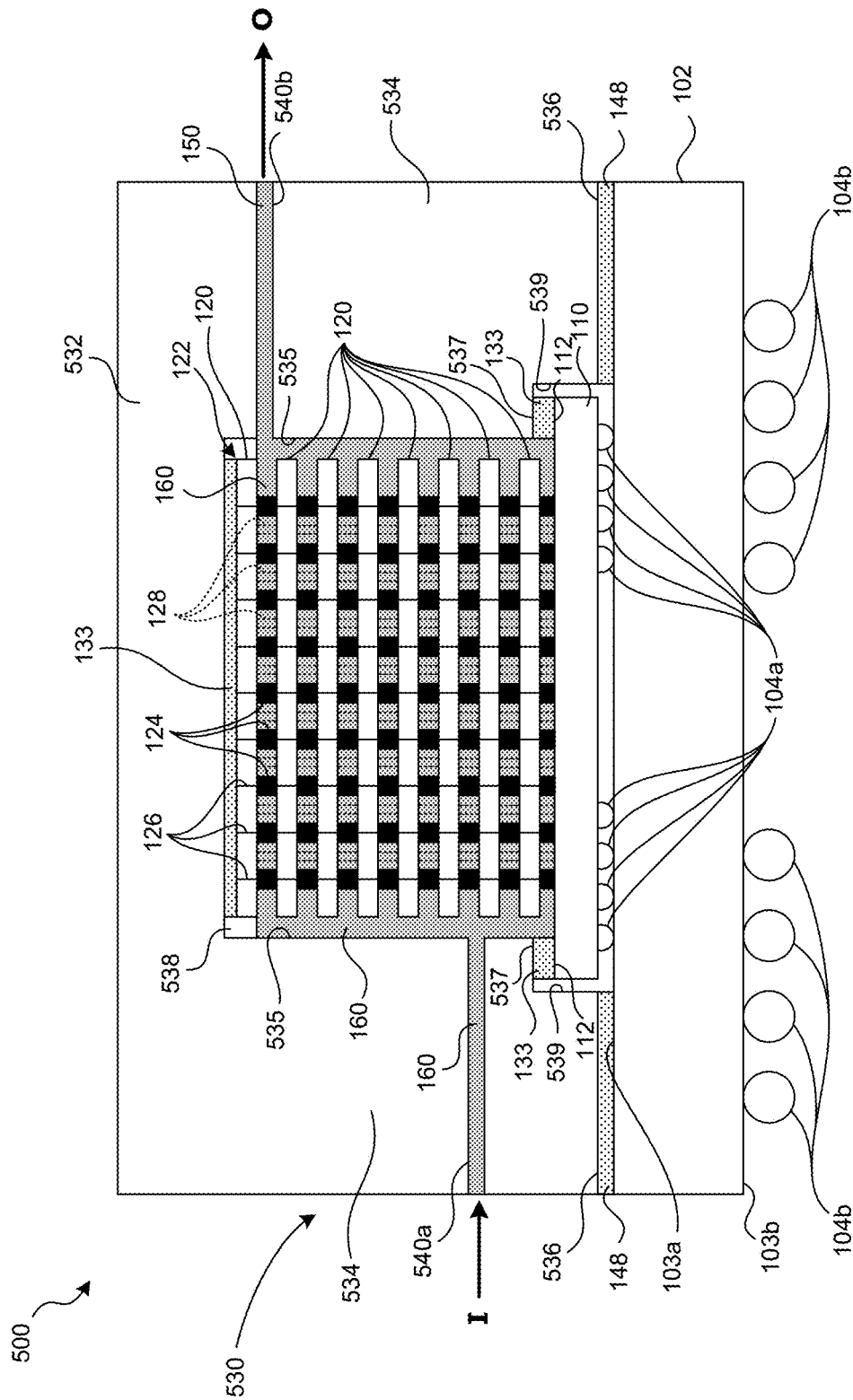


FIG. 5A

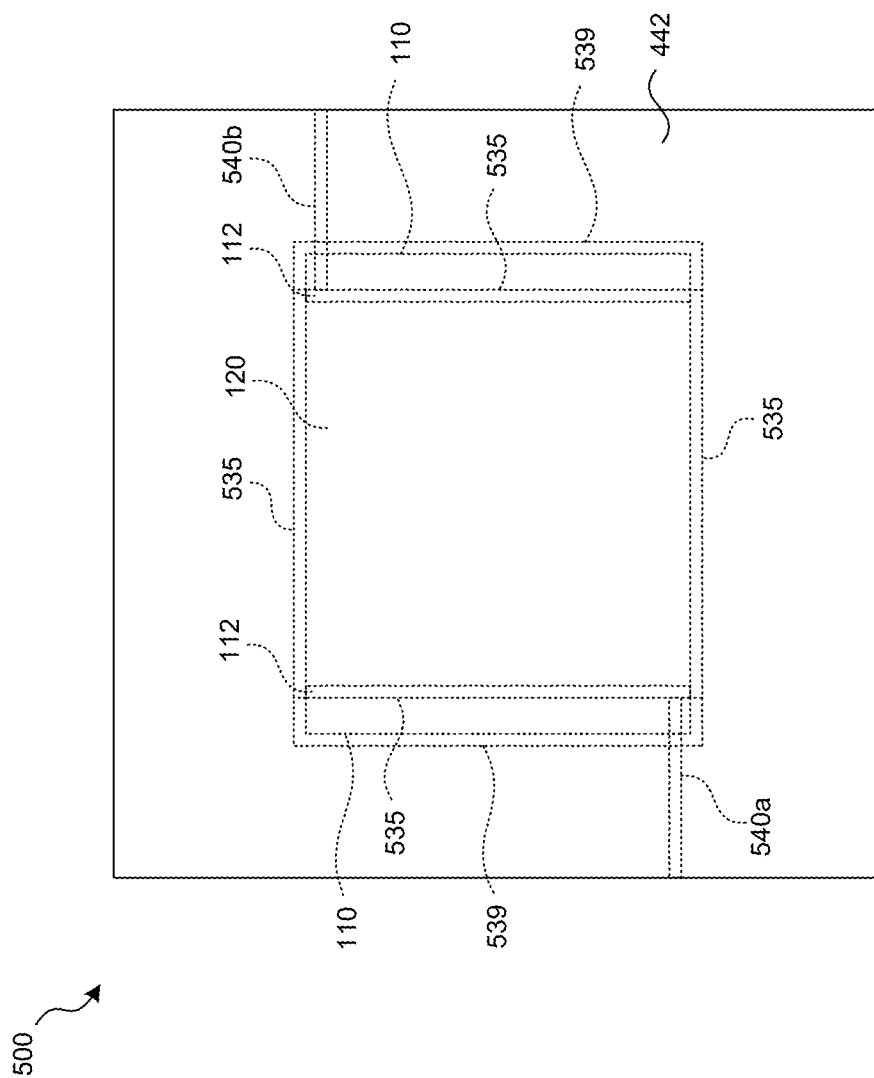


FIG. 5B

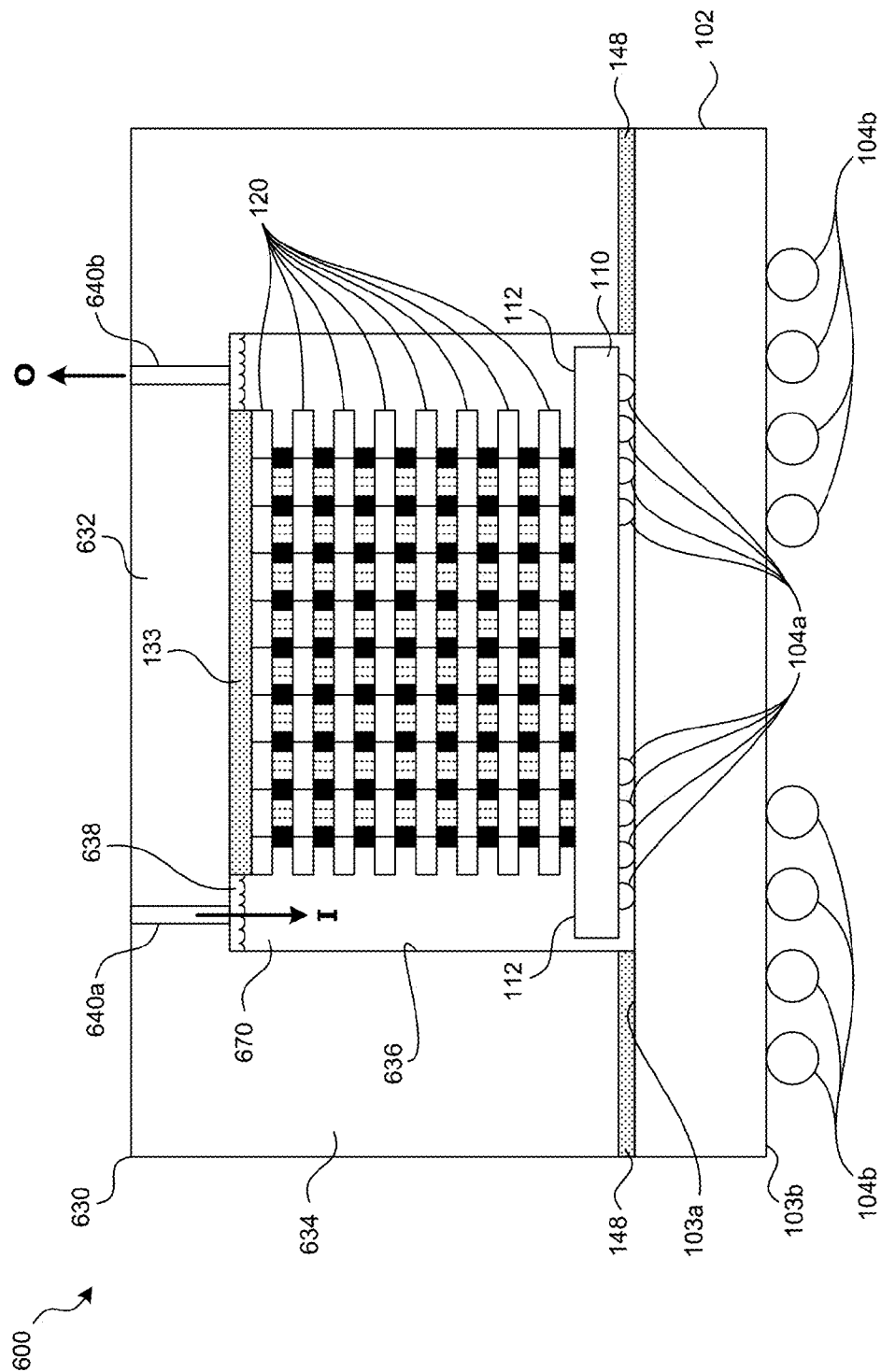


FIG. 6

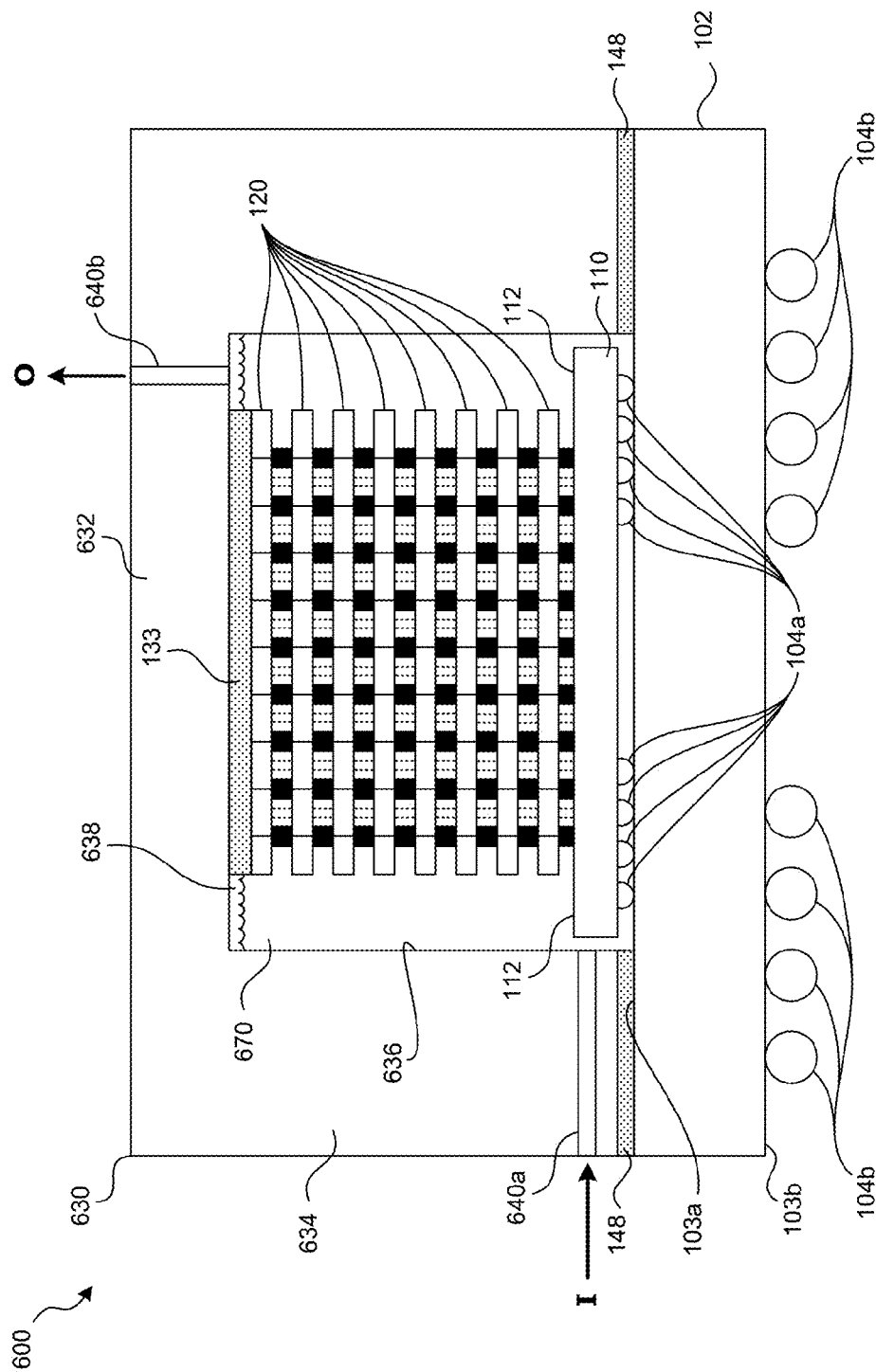


FIG. 7

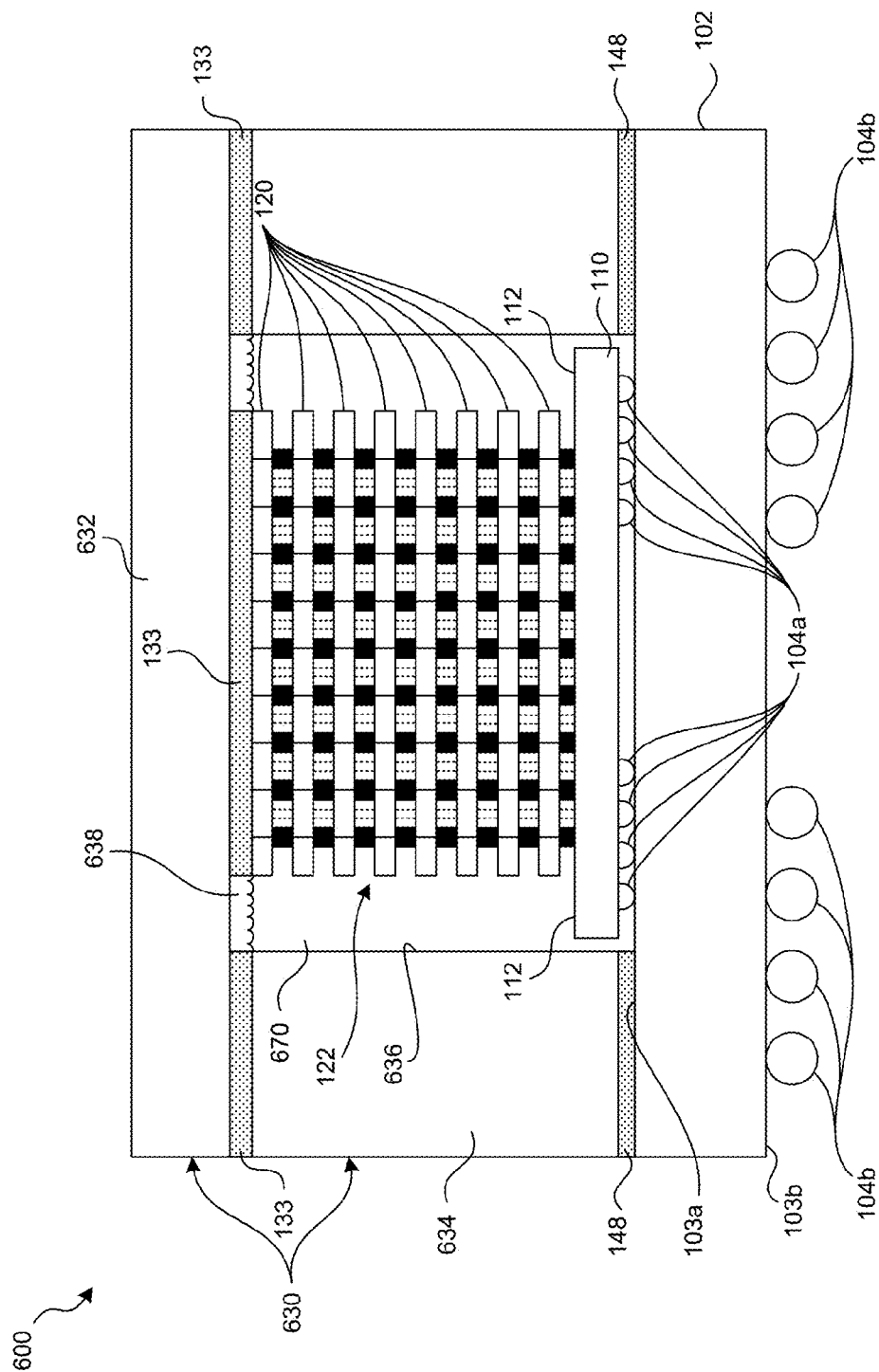


FIG. 8

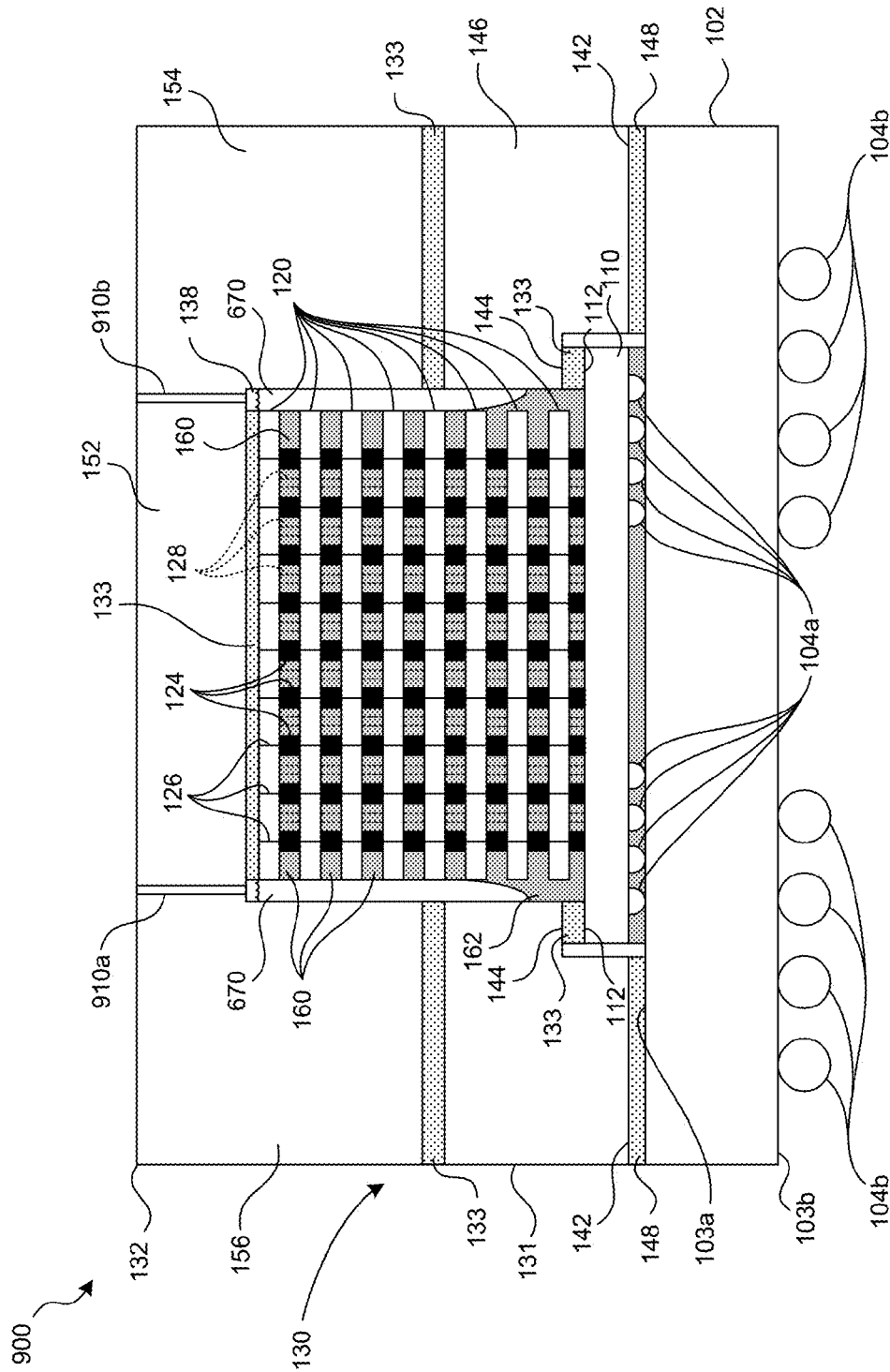
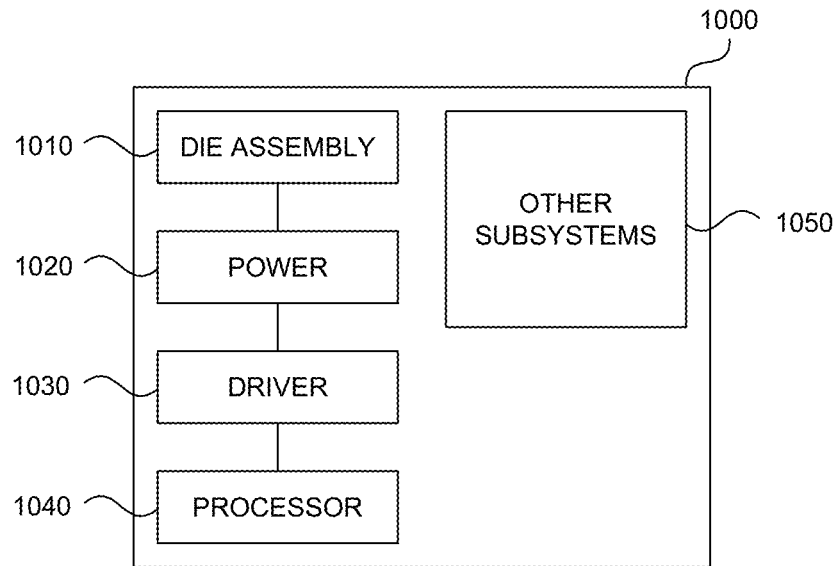


FIG. 9

**FIG. 10**

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STACKED SEMICONDUCTOR DIE ASSEMBLIES WITH HIGH EFFICIENCY THERMAL PATHS AND ASSOCIATED SYSTEMS

TECHNICAL FIELD

The disclosed embodiments relate to semiconductor die assemblies. In particular, the present technology relates to stacked semiconductor die assemblies with highly efficient thermal paths and associated systems and methods.

BACKGROUND

Packaged semiconductor dies, including memory chips, microprocessor chips, and imager chips, typically include a semiconductor die mounted on a substrate and encased in a plastic protective covering. The die includes functional features, such as memory cells, processor circuits, and imager devices, as well as bond pads electrically connected to the functional features. The bond pads can be electrically connected to terminals outside the protective covering to allow the die to be connected to higher level circuitry.

Market pressures continually drive semiconductor manufacturers to reduce the size of die packages to fit within the space constraints of electronic devices, while also pressuring them to increase the functional capacity of each package to meet operating parameters. One approach for increasing the processing power of a semiconductor package without substantially increasing the surface area covered by the package (i.e., the package's "footprint") is to vertically stack multiple semiconductor dies on top of one another in a single package. The dies in such vertically-stacked packages can be interconnected by electrically coupling the bond pads of the individual dies with the bond pads of adjacent dies using through-silicon vias (TSVs).

A challenge associated with vertically-stacked die packages is that the heat from the individual dies is additive and it is difficult to dissipate the aggregated heat generated by the stacked die. This increases the operating temperatures of the individual dies, the junctions between the dies, and the package as a whole, which can cause the stacked dies to reach temperatures above their maximum operating temperatures (Tmax). The problem is also exacerbated as the density of the dies in the package increases. Moreover, when devices have different types of dies in the die stack, the maximum operating temperature of the device is limited to the die with the lowest maximum operating temperature.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a cross-sectional view illustrating a semiconductor die assembly in accordance with embodiments of the present technology.

FIG. 2A is a cross-sectional view and FIG. 2B is a top plan view illustrating a method of manufacturing a semiconductor die assembly in accordance with embodiments of the technology.

FIG. 2C is a cross-sectional view and FIG. 2D is a top plan view illustrating a method of manufacturing a semiconductor die assembly in accordance with embodiments of the technology.

FIGS. 2E and 2F are cross-sectional views illustrating a method of manufacturing a semiconductor die assembly in accordance with embodiments of the technology.

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FIG. 3 is a cross-sectional view illustrating a semiconductor die assembly in accordance with embodiments of the present technology.

FIG. 4A is a cross-sectional view and FIG. 4B is a top plan view illustrating a method of manufacturing a semiconductor die assembly in accordance with embodiments of the technology.

FIG. 4C is a cross-sectional view illustrating a method of manufacturing a semiconductor die assembly in accordance with embodiments of the present technology.

FIG. 4D is a cross-sectional view and FIG. 4E is a top plan view illustrating a method of manufacturing a semiconductor die assembly in accordance with embodiments of the present technology.

FIG. 5A is a cross-sectional view and FIG. 5B is a top plan view of a semiconductor die assembly in accordance with embodiments of the present technology.

FIG. 6 is a cross-sectional view of a semiconductor die assembly in accordance with embodiments of the present technology.

FIG. 7 is a cross-sectional view of a semiconductor die assembly in accordance with embodiments of the present technology.

FIG. 8 is a cross-sectional view of a semiconductor die assembly in accordance with embodiments of the present technology.

FIG. 9 is a cross-sectional view of a semiconductor die assembly in accordance with embodiments of the present technology.

FIG. 10 is a schematic view of a system that includes a semiconductor die assembly configured in accordance with embodiments of the present technology.

DETAILED DESCRIPTION

Specific details of several embodiments of stacked semiconductor die assemblies with highly efficient thermal paths and associated systems and methods are described below. The term "semiconductor die" generally refers to a die having integrated circuits or components, data storage elements, processing components, and/or other features manufactured on semiconductor substrates. For example, semiconductor dies can include integrated circuit memory and/or logic circuitry. Semiconductor dies and/or other features in semiconductor die packages can be said to be in "thermal contact" with one another if the two structures can exchange energy through heat via, for example, conduction, convection and/or radiation. A person skilled in the relevant art will also understand that the technology may have additional embodiments, and that the technology may be practiced without several of the details of the embodiments described below with reference to FIGS. 1-10.

As used herein, the terms "vertical," "lateral," "upper" and "lower" can refer to relative directions or positions of features in the semiconductor die assemblies in view of the orientation shown in the Figures. For example, "upper" or "uppermost" can refer to a feature positioned closer to the top of a page than another feature. These terms, however, should be construed broadly to include semiconductor devices having other orientations, such as inverted or inclined orientations where top/bottom, over/under, above/below, up/down and left/right can be interchanged depending on the orientation.

FIG. 1 is a cross-sectional view illustrating a semiconductor die assembly 100 ("assembly 100") in accordance with an embodiment of the present technology. The assembly 100 can include a package support substrate 102, a first semiconductor die 110 mounted to the package support substrate 102, and

a plurality of second semiconductor dies **120** arranged in a stack **122** at a stacking area, such as a central region or an off-center region, of the first die **110**. The first die **110** can further include a peripheral region **112** laterally outboard of the second dies **120** and a thermal transfer structure (TTS) **130** having a first portion **131** attached to the peripheral region **112** of the first die **110** by an adhesive **133** and a second portion **132** covering, enclosing or otherwise over the stack **122** of second dies **120**. The adhesive **133**, for example, can be a thermal interface material (“TIM”) or another suitable adhesive. For example, TIMs and other adhesives can include silicone-based greases, gels, or adhesives that are doped with conductive materials (e.g., carbon nano-tubes, solder materials, diamond-like carbon (DLC), etc.), as well as phase-change materials. In the embodiment illustrated in FIG. 1, the first portion **131** is a base, such as a dam member, that extends at least from the peripheral region **112** of the first die **110** to a height at an intermediate elevation of the stack **122** of second dies **120**. The second portion **132** is a cover that is attached to the first portion **131** and the uppermost second die **120** by the adhesive **133**. The first portion **131** and second portion **132** together can define a casing made from a metal (e.g., copper or aluminum) or other highly thermally conductive materials, and the first and second portions **131** and **132** together can define a cavity **138** in which the stack **122** of second dies **120** are positioned.

The assembly **100** further includes an underfill material **160** between each of the second dies **120** and between the first die **110** and the bottom second die **120**. The underfill material **160** can form a fillet **162** that extends outwardly from the stack **122** of second dies **120** in a region proximate the first die **110**. The assembly **100** is expected to provide enhanced thermal dissipation of heat from the first die **110** and the stack **122** of second dies **120**. For example, the TTS **130** can be made from a material with a high thermal conductivity to efficiently transfer heat along a first path directly from a large portion of the peripheral region **112** of the first die **110** and along a second path through the second dies **120**. The first portion **131** of the TTS **130** is attached to a large percentage of the available area of the peripheral region **112** of the first die **110** because the first portion **131** provides a dam that prevents the fillet **162** of underfill material **160** from covering a significant percentage of the peripheral region **112**. This enhances the efficiency of the first heat path because, compared to devices where the underfill material is deposited before the first portion **131** is attached to the peripheral region **112** of the first die **110**, more surface area of the peripheral region **112** can be covered by the first portion **131** of the TTS **130**.

Several embodiments of the assembly **100** shown in FIG. 1 can accordingly provide enhanced thermal properties that lower the operating temperatures of the individual dies **110**, **120** in the assembly **100** such that they stay below their designated maximum temperatures (T_{max}). This can be very useful when the assembly **100** is arranged as a hybrid memory cube (HMC) because the first die **110** is generally a larger underlying logic die and the second dies **120** are generally memory dies, and logic dies typically operate at a much higher power level than memory dies (e.g., 5.24 W compared to 0.628 W). The logic die HMC configuration generally concentrates a significant amount of heat at the peripheral region **112** of the first die **110**. The logic die may also have a higher power density at the peripheral region, resulting in a further concentration of heat and higher temperatures at the peripheral region. As such, by coupling a large percentage of the peripheral region **112** of the first die **110** to the highly

conductive first portion **131** of the TTS **130**, the heat can be efficiently removed from the peripheral region **112** of the first die.

FIGS. 2A-2F illustrate aspects of a method of manufacturing the assembly **100** in accordance with embodiments of the present technology. FIG. 2A is a cross-sectional view and FIG. 2B is a top plan view of a stage of manufacturing the assembly **100**. Referring to FIG. 2A, the package support substrate **102** is configured to connect the first and second dies **110**, **120** to external electrical components of higher-level packaging (not shown). For example, the package support substrate **102** can be an interposer or printed circuit board that includes semiconductor components (e.g., doped silicon wafers or gallium arsenide wafers), non-conductive components (e.g., various ceramic substrates, such as aluminum oxide (Al₂O₃), aluminum nitride (AlN), etc.), and/or conductive portions (e.g., interconnecting circuitry, TSVs, etc.). In the embodiment illustrated in FIG. 2A, the package support substrate **102** is electrically coupled to the first die **110** at a first side **103a** of the package support substrate **102** via a first plurality of electrical connectors **104a** and to external circuitry (not shown) at a second side **103b** of the package support substrate **102** via a second plurality of electrical connectors **104b** (collectively referred to as “the electrical connectors **104**”). The electrical connectors **104** can be solder balls, conductive bumps and pillars, conductive epoxies, and/or other suitable electrically conductive elements. In various embodiments, the package support substrate **102** can be made from a material with a relatively high thermal conductivity to enhance heat dissipation at the back side of the first semiconductor die **110**.

As shown in FIGS. 2A and 2B, the first die **110** can have a larger footprint than the stacked second dies **120**. The first die **110**, therefore, includes a mounting region **111** (FIG. 2A) or stacking area where the second dies **120** are attached to the first die **110** and the peripheral region **112** extends laterally outward beyond at least one side of the mounting region **111**. The peripheral region **112** is accordingly outboard of the second dies **120** (e.g., beyond the length and/or width of the second dies **120**).

The first and second dies **110**, **120** can include various types of semiconductor components and functional features, such as dynamic random-access memory (DRAM), static random-access memory (SRAM), flash memory, other forms of integrated circuit memory, processing circuits, imaging components, and/or other semiconductor features. In various embodiments, for example, the assembly **100** can be configured as an HMC in which the stacked second dies **120** are DRAM dies or other memory dies that provide data storage and the first die **110** is a high-speed logic die that provides memory control (e.g., DRAM control) within the HMC. In other embodiments, the first and second dies **110** and **120** may include other semiconductor components and/or the semiconductor components of the individual second dies **120** in the stack **122** may differ.

The first and second dies **110**, **120** can be rectangular, circular, and/or other suitable shapes and may have various different dimensions. For example, the individual second dies **120** can each have a length L_1 of about 10-11 mm (e.g., 10.7 mm) and a width of about 8-9 mm (e.g., 8.6 mm, 8.7 mm). The first die **110** can have a length L_2 of about 12-13 mm (e.g., 12.67 mm) and a width of about 8-9 mm (e.g., 8.5 mm, 8.6 mm, etc.). In other embodiments, the first and second dies **110** and **120** can have other suitable dimensions and/or the individual second dies **120** may have different dimensions from one another.

The peripheral region 112 (known to those skilled in the art as a “porch” or “shelf”) of the first die 110 can be defined by the relative dimensions of the first and second dies 110 and 120 and the position of the stack 122 on a forward-facing surface 114 of the first die 110. In the embodiment illustrated in FIGS. 2A and 2B, the stack 122 is centered with respect to the length L2 of the first die 110 such that the peripheral region 112 extends laterally beyond two opposite sides of the stack 122. For example, if the length L2 of the first die 110 is about 1.0 mm greater than the length L1 of the second dies 120, the peripheral region 112 will extend about 0.5 mm beyond either side of the centered second dies 120. The stack 122 may also be centered with respect to the width of the first die 110 and, in embodiments where both the width and length of the first die 110 are greater than those of the centered stack 122, the peripheral region 112 may extend around the entire perimeter of the second dies 120. In other embodiments, the stack 122 may be offset with respect to the forward-facing surface 114 (FIG. 2A) of the first die 110 and/or the peripheral region 112 of the first die 110 may extend around less than the full perimeter of the stack 122. In further embodiments, the first and second dies 110 and 120 can be circular, and therefore the relative diameters of the first and second dies 110 and 120 define the peripheral region 112.

As shown in FIG. 2A, the second dies 120 can be electrically coupled to one another in the stack 122 and to the underlying first die 110 by a plurality of electrically conductive elements 124 positioned between adjacent dies 110, 120. Although the stack 122 shown in FIG. 1 includes eight second dies 120 electrically coupled together, in other embodiments the stack 122 can include more or less than eight dies (e.g., 2-4 dies, or at least 9 dies etc.). The electrically conductive elements 124 can have various suitable structures, such as pillars, columns, studs, bumps, and can be made from copper, nickel, solder (e.g., SnAg-based solder), conductor-filled epoxy, and/or other electrically conductive materials. In selected embodiments, for example, the electrically conductive elements 124 can be copper pillars, whereas in other

embodiments the electrically conductive elements 124 can include more complex structures, such as bump-on-nitride structures. As further shown in FIG. 2A, the individual second dies 120 can each include a plurality of TSVs 126 aligned on one or both sides with corresponding electrically conductive elements 124 to provide electrical connections at opposing sides of the second dies 120. Each TSV 126 can include an electrically conductive material (e.g., copper) that passes completely through the individual second dies 120 and an electrically insulative material surrounding the electrically conductive material to electrically isolate the TSVs 126 from the remainder of the second dies 120. Though not shown in FIG. 1, the first die 110 can also include a plurality of TSVs 126 to electrically couple the first die 110 to higher level circuitry. Beyond electrical communication, the TSVs 126 and the electrically conductive elements 124 provide thermal conduits through which heat can be transferred away from the first and second dies 110 and 120 (e.g., through the first thermal path). In some embodiments, the dimensions of the electrically conductive elements 124 and/or the TSVs 126 can be increased to enhance heat transfer vertically through the stack 122. For example, the individual electrically conductive elements 124 can each have a diameter of about 15-30 μm or other suitable dimensions to enhance the thermal pathway through the dies 110, 120. In other embodiments, the second dies 120 can be electrically coupled to one another and to the

first die 110 using other types of electrical connectors (e.g., wirebonds) that may also provide thermal pathways through the stack 122.

In various embodiments, the assembly 100 may also include a plurality of thermally conductive elements 128 (shown in broken lines) positioned interstitially between the electrically conductive elements 124. The individual thermally conductive elements 128 can be at least generally similar in structure and composition as that of the electrically conductive elements 124 (e.g., copper pillars). However, the thermally conductive elements 128 are not electrically coupled to the TSVs 126 or other electrically active components of the dies 110 and 120, and therefore do not provide electrical connections between the second dies 120. Instead, the thermally conductive elements 128 are electrically isolated “dumb elements” that increase the overall thermal conductivity through the stack 122 to enhance the heat transfer along a first thermal path. For example, in embodiments where the assembly 100 is configured as a HMC, the addition of the thermally conductive elements 128 between the electrically conductive elements 124 has been shown to decrease the operating temperature of the HMC by several degrees (e.g., about 6-7° C.).

FIG. 2C is a cross-sectional view and FIG. 2D is a top plan view illustrating a subsequent stage of a method for manufacturing the assembly 100 after the first portion 131 of the TTS 130 (FIG. 1) has been attached to the first die 110 and the package support substrate 102. Referring to FIG. 2C, this embodiment of the first portion 131 has a foundation 142 (e.g., footing) configured to extend around at least a portion of the first die 110 and a shoulder 144 configured to be positioned over the peripheral region 112 of the first die 110. The first portion 131 can further include a sidewall 146 that extends to a height (H1) relative to the stack 122 of second dies 120. The sidewall 146 is also spaced apart from the stack 122 of second dies 120 by a gap (G) such that the shoulder 144 covers a significant percentage of the peripheral region 112 (e.g., coverage area (C)). The foundation 142 can be attached to the package support substrate 102 by an adhesive 148, and the shoulder 144 can be attached to the peripheral region 112 of the first die 110 by the thermally conductive adhesive 133. The adhesives 133 and 148 can be the same adhesive, or they can be different from each other. The adhesive 133, for example, can be a TIM. As shown in FIG. 2D, the first portion 131 can be a ring that surrounds the first die 110 and the second dies 120.

FIG. 2E is a cross-sectional view illustrating another stage of the method of manufacturing the assembly 100 after the underfill material 160 has been deposited between the second dies 120 and between the first die 110 and the bottom second die 120. The underfill material 160 is typically a flowable material that fills the interstitial spaces between the second dies 120, the electrically conductive elements 124, and the thermally conductive elements 128. The first portion 131 of the TTS 130 provides a dam member that inhibits the extent that the fillet 162 covers the peripheral region 112 of the first die 110. For example, instead of the fillet 162 spreading laterally over the peripheral region 112 as in other devices that attach a thermally conductive member to the peripheral region 112 after depositing the underfill material 160, the fillet 162 extends upwardly along a portion of the sidewall 146. The underfill material 160 can be a non-conductive epoxy paste (e.g., XS8448-171 manufactured by Namics Corporation of Niigata, Japan), a capillary underfill, a non-conductive film, a molded underfill, and/or include other suitable electrically-insulative materials. The underfill material 160 can alternatively be a dielectric underfill, such as FP4585

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manufactured by Henkel of Dusseldorf, Germany. In some embodiments, the underfill material 160 can be selected based on its thermal conductivity to enhance heat dissipation through the stack 122. The volume of underfill material 160 is selected to adequately fill the interstitial spaces such that an excess portion of the underfill material 160 goes into the gap (G) between the sidewall 146 of the first portion 131 and the stack 122 of second dies 120 to form the fillet 162. The height (H1), gap (G), and coverage area (C), are selected to provide a large coverage area (C) of the peripheral region 112 while also providing sufficient space between the sidewall 146 and the stack 122 of second dies 120 to accommodate the fillet 162 of underfill material 160.

FIG. 2F is a cross-sectional view illustrating the assembly 100 of FIG. 1 after the second portion 132 of the TTS 130 has been attached to the first portion 131 to complete the TTS 130. The second portion 132 can have a top 152 attached to the uppermost second die 120 by the adhesive 133, a bottom 154 attached to the first portion 131 by the adhesive 133, and a sidewall 156 pendent from the top 152. The first portion 131 and second portion 132 together define the cavity 138 which encases the stack 122 of second dies 120. The TTS 130 of the embodiment illustrated in FIG. 2F is accordingly a thermally conductive casing that provides enhanced heat transfer to remove heat generated by the first die 110 and the second dies 120. Each of the first portion 131 and the second portion 132 of the TTS 130 can be made from metal, such as copper or aluminum, such that the TTS 130 has a metal base portion and a metal cover.

FIG. 3 is a cross-sectional view of another embodiment of the assembly 100 in accordance with the present technology. In this embodiment, the first portion 131 of the TTS 130 has a sidewall 146 with a height (H2) that extends to at least approximately the same elevation as the top of the uppermost second die 120, and the second portion 132 of the TTS 130 has a bottom 154 attached to the top of the sidewall 146. The second portion 132 accordingly does not have a separate sidewall pendent from the top 152. The second portion 132 can be attached to the first portion 131 by the adhesive 133.

FIG. 4A is a side cross-sectional view and FIG. 4B is a top plan view of a semiconductor die assembly 400 at one stage of a manufacturing process in accordance with the present technology. Several features of the assembly 400 are similar to those described above with respect to the assembly 100, and thus like reference numbers refer to like components in FIGS. 1-4B. FIG. 4A shows the assembly 400 after an inner casing 430 has been attached to the first die 110. The inner casing 430 can include a first support 431 with a first interior surface 433, a second support 432 with a second interior surface 434, and a top 435 extending between the first and second supports 431 and 432. The inner casing 430 has a cavity 436 that is closed on the sides with the first and second supports 431 and 432, but open on the other two sides. The first and second supports 431 and 432 can be attached to the peripheral region 112 of the first die 110 with the adhesive 133. The top 435 of the inner casing 430 can also be attached to the top of the second die 120 by the adhesive 133. As shown in FIG. 4B, the inner casing 430 can have a footprint similar to the footprint of the first die 110.

FIG. 4C is a side cross-sectional view of the assembly 400 at a subsequent stage of manufacturing after the underfill material 160 has been deposited between the second dies 120 and between the first die 110 and the bottom second die 120. Referring back to FIG. 4B, the underfill material can be distributed within the interstitial spaces by flowing the underfill material through the open sides of the inner casing 430 as shown by arrow F. To enhance the flow of underfill material,

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the assembly 400 can be inclined at an angle such that gravity pulls the underfill material 160 through the interstitial spaces within the cavity 436.

FIG. 4D is a side cross-sectional view and FIG. 4E is a top plan view of the assembly 400 at a subsequent stage of manufacturing. Referring to FIG. 4D, the assembly 400 further includes an outer casing 440 having a sidewall 442 with an inner surface 444 and a top 446 that together define a cavity 448. As shown in FIG. 4E, the inner surface 444 of the sidewall 442 has four sides such that the cavity 448 encloses the first die 110, the stack of second dies 120, and the inner casing 430. As shown in FIG. 4D, the outer casing 440 can be attached to the package support substrate 102 by the adhesive 148 and to the top 435 of the inner casing 430 by the adhesive 133. This embodiment provides a good thermal interface with the peripheral region 112 of the first die 110 as explained above and with the sides of the second dies 120 because the underfill material 160 can have a higher thermal conductivity than a void in within the casing.

FIG. 5A is a cross-sectional view and FIG. 5B is a top plan view of a semiconductor device assembly 500 ("assembly 500") in accordance with another embodiment of the present technology. Like reference numbers refer to like components throughout FIGS. 1-5B. The assembly 500 includes a TTS 530 having a top 532, a sidewall 534 integrally formed with the top 532, and a cavity 538 defined by the top 532 and the sidewall 534. The TTS 530 is a single-piece casing formed from a material having a high thermal conductivity, such as copper or aluminum. The sidewall 534 can have an interior surface 535. In one embodiment as shown in FIG. 5B, the interior surface 535 can have four sides configured to be spaced apart from the stack 122 of second dies 120 such that a small gap exists between the second dies 120 and the interior surface 535 of the sidewall 534. Referring back to FIG. 5A, the sidewall 534 can further include a foundation 536 attached to the package support substrate 102 by the adhesive 148 and a shoulder 537 attached to the peripheral region 112 of the first die 110 by the adhesive 133. The foundation 536 can be a footing that has an inner surface 539 spaced laterally outward from the peripheral region 112 of the first die 110. The TTS 530 can further include an inlet 540a and an outlet 540b. The inlet 540a can be a first passageway extending through a lower portion of the sidewall 534, and the outlet 540b can be a second passageway that extends through an upper portion of the sidewall 534. Referring to FIG. 5B, the inlet 540a and the outlet 540b can be laterally offset from each other, or in other embodiments they can be aligned with each other across the cavity 538. In other embodiments, the inlet 540a and outlet 540b can extend through the sidewall at approximately the same elevation. In still other embodiments, the inlet 540a can be positioned relatively higher along the sidewall 534 than the outlet 540b.

The underfill material 160 is injected (I) into the cavity 538 via the inlet 540a such that the underfill material 160 fills the interstitial spaces between the second dies 120 and between the first die and the bottom second die 120. In one embodiment, the underfill material 160 can be injected into the cavity 538 until the underfill material 160 flows out of the outlet 540b (O). The inlet 540a and outlet 540b can be sealed by filling these passageways with the underfill material 160, or in other embodiments the exterior openings of the inlet 540a and outlet 540b can be capped with another material to seal the cavity 538 within the TTS 530. As a result, the TTS 530 provides a dam member that effectively contains the underfill material 160 while also providing coverage of a large surface area of the peripheral region 112 of the first die 110 by the shoulder 537 of the sidewall 534. Moreover, the underfill

material **160** also contacts the sides of the second die **120** to also enhance the heat transfer laterally away from the second dies **120**.

FIG. 6 is a cross-sectional view of a semiconductor die assembly **600** ("assembly **600**") in accordance with another embodiment of the present technology. Like reference number refer to like components in FIGS. 1-6. The assembly **600** can include a TTS **630** having a top **632** and a sidewall **634** having an interior surface **636**. The top **632** and the sidewall **634** define a cavity **638** configured to receive the first die **110** and the stack **122** of second dies **120**. The top **632** can be attached to the upper second die **120** by the adhesive **133**, and the sidewall **634** can be attached to the package support substrate **102** by the adhesive **148**. The embodiment of the sidewall **634** shown in FIG. 6 does not contact the peripheral region **112** of the first die **110**. In other embodiments, the sidewall **634** can have a shoulder adhered to the peripheral region **112** of the first die **110** and a foundation adhered to the package support substrate **102** as shown by the shoulder **537** and foundation **536** of the sidewall **534** show in FIG. 5A. The TTS **630** can further include an inlet **640a** and an outlet **640b**. In the illustrated embodiment, the inlet **640a** and outlet **640b** are passageways that extend through the top **632** of the TTS **630**. In other embodiments, the inlet **640a** and/or the outlet **640b** can be passageways through the sidewall **634**. Additionally, the embodiment of the TTS **630** illustrated in FIG. 6 is a single-piece casing in which the top **632** is formed integrally with the sidewall **634**. In other embodiments, the top **632** can be a separate component that is attached to the sidewall **634** by an adhesive, such as shown and described with respect to FIG. 3.

The assembly **600** further includes a thermally conductive dielectric liquid **670** in the cavity **638**. The dielectric liquid **670** can be injected into the cavity **638** (I) via the inlet **640a**. The outlet **640b** can accordingly provide a vent through which air or other matter can escape (O) from the cavity **638** as the dielectric liquid **670** is injected. The dielectric liquid **670** can be injected as a liquid and remain in the liquid state within the cavity **638**, or it can be injected as a liquid and partially cured to a gel-like substance or fully cured to a solid. Suitable thermally conductive dielectric liquids **670** include, for example, paraffin fluid and DowthermTM manufactured by the Dow Chemical Company. Suitable DowthermTM heat transfer fluids include Dowtherm ATM, Dowtherm GTM, Dowtherm QTM and Dowtherm TTM, all of which are manufactured by the Dow Chemical Company. The dielectric liquid **670** should have a boiling point greater than the maximum operating temperature of the assembly **600** to avoid generating a gas in the cavity. In some embodiments, the dielectric liquid **670** can be selected to cure to a solid or semi-solid material at ambient temperatures, but undergo a phase change to a liquid state at or near maximum operating temperatures to potentially enhance the heat transfer and provide a steady state operating temperature when maximum operating temperatures are reached.

The dielectric liquid **670** can fill the interstitial spaces between the second dies **120** and between the first die **110** and the bottom second die **120** such that a separate underfill material is not necessarily required. In other embodiments, an underfill material may be deposited between the second dies **120** and between the first die **110** and the bottom second die **120** before filling the cavity **638** with the dielectric liquid **670**. The underfill material is generally desirable when the dielectric liquid **670** remains in the liquid state to provide structural support for the dies **110**, **120**. However, the underfill material can be eliminated when the dielectric liquid **670** cures to a sufficiently solid state.

In operation, the dielectric liquid **670** contacts not only the peripheral region **112** of the first die **110**, but also the second dies **120** to efficiently transfer heat to the TTS **630**. This provides significantly more surface contact between a material with high thermal conductivity and the dies **110** and **120** compared to devices that use an underfill material and/or have voids between the casing and the dies **110** and **120**. In some embodiments, the cavity **638** is completely filled to prevent voids within the TTS **630**, and the inlet **640a** and outlet **640b** are capped to seal the cavity **638**. The embodiment of the assembly **600** is expected to provide highly efficient heat transfer from the first and second dies **110** and **120**.

FIG. 7 is a cross-sectional view of another embodiment of the assembly **600** in accordance with the present technology. In this embodiment, the inlet **640a** is a passageway extending through a lower portion of the sidewall **634** and the outlet **640b** is a passageway extending through the top **632**. This embodiment provides bottom up filling of the cavity **638**, which is expected to mitigate the possible formation of air pockets within the cavity **638**.

FIG. 8 is a cross-sectional view illustrating another embodiment of the assembly **600** in accordance with the present technology. In this embodiment, the TTS **630** is a multi-piece casing having a top component **632** and a separate sidewall **634** that are attached to each other by the adhesive **133**. The sidewall **634** can be attached to the package support substrate **102** by the adhesive **148**, and then the space between the interior surface **636** of the sidewall **634** and the dies **110** and **120** can be filled with the dielectric liquid **670**. The top **632** is then attached to the sidewall **634** and the upper second die **120** by the adhesive **133**. In many embodiments, the cavity **638** will have a small void caused by the thickness of the adhesives **133**. To avoid having an expandable gas within the cavity **638**, the top **632** of the TTS **630** can be attached to the sidewall **634** in a vacuum.

FIG. 9 is a cross-sectional view of a semiconductor die assembly **900** ("assembly **900**") in accordance with another embodiment of the present technology. The embodiment illustrated in FIG. 9 is similar to the embodiment of the assembly **100** illustrated in FIG. 2F, and therefore like reference numbers refer to like components in FIGS. 1-9. In the assembly **900**, the TTS **130** can further include an inlet **910a** and an outlet **910b** in the second portion **132** of the TTS **130**. The inlet **910a** and outlet **910b** are passageways that are exposed to the cavity **138** within the TTS **130**. The assembly **900** further includes both the underfill material **160** and the dielectric liquid **670** in the cavity **138**. The underfill material **160** can be deposited as described above with reference to FIG. 2E. The dielectric liquid **670** can be injected into the cavity via the inlet **910a**, and air or excess dielectric liquid **670** can pass out of the cavity **138** via the outlet **910b**. After the cavity **138** has been filled with the dielectric liquid **670**, the inlet **910a** and outlet **910b** can be capped or otherwise sealed to seal the cavity **138** from the external environment.

Any one of the stacked semiconductor die assemblies described above with reference to FIGS. 1-9 can be incorporated into any of a myriad of larger and/or more complex systems, a representative example of which is system **1000** shown schematically in FIG. 10. The system **1000** can include a semiconductor die assembly **1010**, a power source **1020**, a driver **1030**, a processor **1040**, and/or other subsystems or components **1050**. The semiconductor die assembly **1010** can include features generally similar to those of the stacked semiconductor die assemblies described above, and can therefore include multiple thermal paths with good coverage of the peripheral region **112** of the first die **110** that enhance heat dissipation. The resulting system **1000** can perform any

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of a wide variety of functions, such as memory storage, data processing, and/or other suitable functions. Accordingly, representative systems **1000** can include, without limitation, hand-held devices (e.g., mobile phones, tablets, digital readers, and digital audio players), computers, and appliances. Components of the system **1000** may be housed in a single unit or distributed over multiple, interconnected units (e.g., through a communications network). The components of the system **1000** can also include remote devices and any of a wide variety of computer readable media.

From the foregoing, it will be appreciated that specific embodiments of the technology have been described herein for purposes of illustration, but that various modifications may be made without deviating from the disclosure. For example, although many of the embodiments of the semiconductor dies assemblies are described with respect to HMCs, in other embodiments the semiconductor die assemblies can be configured as other memory devices or other types of stacked die assemblies. In addition, the semiconductor die assemblies illustrated in FIGS. 1-9 include a plurality of first semiconductor dies arranged in a stack on the second semiconductor die. In other embodiments, however, the semiconductor die assemblies can include one first semiconductor die stacked on one or more of the second semiconductor dies. Certain aspects of the new technology described in the context of particular embodiments may also be combined or eliminated in other embodiments. Moreover, although advantages associated with certain embodiments of the new technology have been described in the context of those embodiments, other embodiments may also exhibit such advantages and not all embodiments need necessarily exhibit such advantages to fall within the scope of the technology. Accordingly, the disclosure and associated technology can encompass other embodiments not expressly shown or described herein.

We claim:

1. A semiconductor die assembly, comprising:
 - a package support substrate;
 - a first semiconductor die electrically mounted to the package support substrate, the first die having a stacking site and a peripheral region extending laterally from the stacking site;
 - a plurality of second semiconductor dies stacked on each other, wherein a bottom second semiconductor die is attached to the stacking site of the first die;
 - a thermal transfer structure attached to the peripheral region of the first die, the thermal transfer structure having a cavity in which the second dies are positioned and an inlet; and
 - an underfill material in the cavity, wherein the underfill material has a fillet between the second semiconductor dies and the thermal transfer structure caused by injecting the underfill material into the cavity through the inlet such that at least a portion of the fillet extends upward along the thermal transfer structure.
2. The semiconductor die assembly of claim 1 wherein the thermal transfer structure comprises a sidewall attached to the peripheral region of the first die and a top over the sidewall and attached to an uppermost second die, and wherein the sidewall and the top are integrally formed with each other.
3. The semiconductor die assembly of claim 2 wherein the thermal transfer structure comprises a sidewall attached to the peripheral region of the first die and a top over the sidewall and attached to an uppermost second die, and wherein the sidewall and top are separate components that are attached to each other with an adhesive.

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4. The semiconductor die assembly of claim 1 wherein:
 - the thermal transfer structure comprises a sidewall and a top over the sidewall;
 - the inlet comprises a first passageway;
 - the second dies include an uppermost second die above the bottom second die;
 - the underfill material extends upward along the thermal transfer structure to a level at least proximate the uppermost second die; and
 - the semiconductor die assembly further comprises an outlet comprising a second passageway.
5. The semiconductor die assembly of claim 4 wherein the first passageway extends through a lower portion of the sidewall and the second passageway extends through an upper portion of the sidewall.
6. The semiconductor die assembly of claim 4 wherein the first passageway and the second passageway extend through the sidewall at approximately the same elevation.
7. The semiconductor die assembly of claim 4 wherein the first passageway extends through the sidewall and the second passageway extends through the top.
8. The semiconductor die assembly of claim 7 wherein the first passageway extends through a lower portion of the sidewall.
9. The semiconductor die assembly of claim 4 wherein the first passageway extends through the top and the second passageway extends through the top.
10. The semiconductor die assembly of claim 1, further comprising a dielectric liquid injected into the cavity via the inlet, and wherein the dielectric liquid has a higher thermal conductivity than the underfill material.
11. A semiconductor die assembly, comprising:
 - a package support substrate;
 - a first semiconductor die mounted to the package support substrate, the first die having a peripheral region and a stacking area;
 - a plurality of second semiconductor dies including a bottom second die attached to the stacking area of the first die and an upper second die stacked above the lower die;
 - a thermally conductive casing having a base portion attached to the peripheral region of the first die, a top attached to the upper second die, and an inlet; and
 - an underfill material in the casing between the base portion and at least the lower second die, wherein the underfill material is injected into the cavity via the inlet.
12. The semiconductor die assembly of claim 11 wherein the base and the top are integrally formed with each other.
13. The semiconductor die assembly of claim 11 wherein the base and the top are separate components, and the top is attached to the base by an adhesive.
14. The semiconductor die assembly of claim 11 wherein the inlet is a first passageway, and the device further comprises an outlet defined by a second passageway.
15. The semiconductor die assembly of claim 14 wherein the base comprises a portion of a sidewall, and the first passageway extends through a lower area of the sidewall and the second passageway extends through an upper area of the sidewall.
16. The semiconductor die assembly of claim 14 wherein the first and second passageways extend through the top.
17. The semiconductor die assembly of claim 11, further comprising a dielectric liquid in the cavity.
18. The semiconductor die assembly of claim 11 wherein the underfill material at least partially obscures at least a portion of the inlet.
19. A semiconductor die assembly, comprising:
 - a first die having a first functionality, the first die having a peripheral region and a stacking site;

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a plurality of second dies arranged in a stack and mounted to the stacking site of the first die;
 a thermal transfer structure attached to at least the peripheral region of the first die, the thermal transfer structure having a cavity in which the second dies are positioned and an inlet; and
 an underfill material in the cavity between the second dies, wherein the underfill material extends a distance upward along the thermal transfer structure.

20. The semiconductor die assembly of claim 19 wherein the thermal transfer structure has a first portion that includes a foundation configured to extend around at least a portion of the first die and a shoulder configured to be positioned over the peripheral region of the first die, and wherein the shoulder is adhered to the peripheral region of the first die.

21. The semiconductor die assembly of claim 19 wherein the thermal transfer structure comprises:

- a first portion having a foundation configured to extend around at least a portion of the first die and a shoulder configured to be positioned over the peripheral region of the first die, and wherein the shoulder is adhered to the peripheral region of the first die; and
- a second portion attached to the first portion, and the second portion having a top attached to an uppermost second die.

22. The semiconductor die assembly of claim 19 wherein the thermal transfer structure comprises a sidewall and a top,

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the inlet comprises a first passageway, and the semiconductor die assembly comprises an outlet defined by a second passageway.

23. The semiconductor die assembly of claim 22 wherein the sidewall has a foundation configured to be attached to a package support substrate and a shoulder adhered to the peripheral region of the first die.

24. The semiconductor die assembly of claim 22 wherein the first passageway extends through a lower portion of the sidewall and the second passageway extends through an upper portion of the sidewall.

25. The semiconductor die assembly of claim 22 wherein the first passageway extends through the sidewall and the second passageway extends through the top.

26. The semiconductor die assembly of claim 22 wherein the first and second passageways extend through the top.

27. The semiconductor die assembly of claim 19, further comprising a dielectric liquid in the cavity of the thermal transfer structure, and wherein the dielectric liquid has a higher thermal conductivity than the underfill material.

28. The semiconductor die assembly of claim 19 wherein the plurality of second dies includes a bottom second die mounted to the stacking site of the first die and an uppermost second die, and wherein the underfill material extends upward along the thermal transfer structure to an elevation at least proximate the uppermost second die.

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